S29GL-S (Pb Package)

3 Volt-Only Flash Memory with Page Mode featuring 65 nm MirrorBit[®] Process Technology Device Documentation



Supplement

General Description

This supplementary document provides information on a device designed for limited distribution. It describes how the features, operation, and ordering options of this device have been enhanced or changed from the standard device on which it is based. The information contained in this document modifies any information on the same topics established by the data sheets listed in the Affected Documents/Related Documents table and should be used in conjunction with those documents. This document may also contain information that was not previously covered by the S29GL-S data sheet. It is intended for hardware system designers and software developers of applications, operating systems, or tools.

Affected Documents/Related Documents

Title	Publication Number
S29GL-S MirrorBit Flash Family Data Sheet	S29GL_128S_01GS_00



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1. Device Description

None.

2. Device Bus Operation Changed

None.

3. Embedded Algorithm Performance None.

4. Electrical Specifications

None.

5. Timing Specifications

None.



6. Ordering Information

Valid Combinations

The Recommended Combinations table lists configurations planned to be available in volume. The table below will be updated as new combinations are released. Consult your local sales representative to confirm availability of specific combinations and to check on newly released combinations.

S29GL-S Valid Combinations								
Base OPN	Speed (ns)	Package and Temperature	Model Number	Packing Type	Ordering Part Number (yy = Model Number, x = Packing Type)			
S29GL01GS	100	FAI (Note 1)	01, 02	0, 3 (Note 2)	S29GL01GS10FAlyyx			
529GL01G5	110		V1, V2		S29GL01GS11FAlyyx			
00001 5400	100		01, 02		S29GL512S10FAlyyx			
S29GL512S	110		V1, V2		S29GL512S11FAlyyx			
S2001 2565	90		01, 02		S29GL256S10FAlyyx			
S29GL256S	100		V1, V2		S29GL256S90FAlyyx			
S29GL128S	90		01, 02	1	S29GL128S10FAlyyx			
529GL1285	100		V1, V2	1	S29GL128S90FAlyyx			

Notes:

1. Additional speed, package, and temperature options maybe offered in the future. Check with your local sales representative for availability.

2. Package Type 0 is standard option.



The ordering part number for the device is formed by a valid combination of the following:



3.0 Volt Core, with $\rm V_{IO}$ Option, 1024, 512, 256, 128 Megabit Page-Mode Flash Memory, Manufactured on 65 nm MirrorBit Eclipse Process Technology



7. Revision History

Section	Description			
Revision 01 (October 21, 2011)				
	Initial release			
Revision 02 (December 14, 2011)				
Ordering Information	Updated Valid Combinations table			
Revision 03 (April 17, 2012)				
Ordering Information	Updated Valid Combinations table			



Colophon

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